## **Product/Process Change Notifications**



Amphenol FCI is part of AICC Group

## PCN - 17 096

Release Date: December 05 2017

DDR4 SMT Product Name: DDR4 SMT Bonnie Liu Product Manager: Notification of Change with Immediate Effectivity Subject: IBM Distribution: Type of Change: Process Change Due to there is no supporting plane in the area A of DDR4 SMT housing, it is the open slot ,the dimension of A near to lower specification limit 1.51 mm (Spec 1.51 -1.64mm) before reflow, after reflow and shrinkage become larger, that cause the dim out of spec after reflow Although area A dimension is out of specification, the insertion force of module card can meet the spec. Max 106.8N. Gap at (C) Test Condition/ Gap at (B) More in center of D/c P/N Gap Data (mm) Gap at (A) Near first connector Change Description: Insertion Force Top of Tab A contact gap Before reflow 1.513 1.553 1.583 2017/8/4 10124677-0101E13LF 57N After reflow 1.462 1.552 1.579 -0.004 Delta -0.051 -0.001 1.537 1.53 Before reflow 1.51 2017/8/11 10124677-0100E13LF After Reflow 1.446 1.526 1.522 51N -0.011 -0.008 Delta -0.06 Reason for Change: To ensure dimesnion within spec before and after reflow. Affected Parts: 10124677 Effective Date of Change: January 1, 2018 Last Time Buy Date: Earliest Disty Return Date: Last Time Shipment Date Datasheet Attached? NA Qual/Test Data Attached? NA Samples Availability Date: November 27 2017 Available Alternatives? N/A Contact your local AICC Representative, or Product Manager Questions? Bonnie Liu / Product Manager +86 769 88669459/ Bonnie.liu@fci.com

Note:

Customers should contact Product Manager (or their local AFCI /AICC Representative) directly regarding any concern on the PCN. Lack of any such customer feedback within three weeks of PCN release date will be interpreted as non-objection.